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TABLE OF CONTENTS

A Comprehensive Methodology for Optimizing Power Integrity of High-Performance IC Packages.....	1
<i>Wei Liu, Guang Chen, Qian Ding, Jenny Jiang</i>	
Adaptive Gramian-Angular-Field Segmentation Integration Based Generative Adversarial Network (AGSI-GAN) for Eye Diagram Estimation of High Bandwidth Memory (HBM) Interposer.....	4
<i>Junghyun Lee, Seonguk Choi, Seonguk Son, Joonsang Park, Hyunwoo Kim, Keunwoo Kim, Taein Shin, Boogyo Sim, Jonghyun Hong, Jiwon Yoon, Juneyoung Kim, Joungho Kim</i>	
Knowledge Distillation and Multi-Task Feature Learning for Partial Discharge Recognition.....	7
<i>Jinsheng Ji, Zhou Shu, Hongqun Li, Kai Xian Lai, Yuanjin Zheng, Xudong Jiang</i>	
Recent Progress on Signal Integrity Modeling of Neuromorphic Chips by the PEEC Method.....	10
<i>Hanzhi Ma, Tuomin Tao, Quankun Chen, Da Li, Jose Schutt-Aine, Andreas Cangelaris, Er-Ping Li</i>	
Causal Or Not? A Definite Answer for Frequency-Response Data.....	13
<i>Andria Lemus, Arif Ege Engin</i>	
Fast Frequency-Domain Analysis for Parametric Electromagnetic Models Using Deep Learning.....	16
<i>Elia Mattucci, Lihong Feng, Peter Benner, Daniele Romano, Giulio Antonini</i>	
CISPR 25 Conducted Emission Simulation and Measurement Correlation of an Automotive Isolated Solid-State Relay.....	19
<i>Jie Chen, Rajen Murugan, John Broze, Premsagar Kittur, Bryan Marshall, Tilden Chen, Alex Triano, Bibhu Nayak, Harikiran Muniganti, Joe Sivaswamy, Dipanjan Gope</i>	
Fast Electromagnetic Analysis of Multiscale Interconnect Networks Using MultiAIM.....	22
<i>Yongzhong Li, Damian Marek, Piero Triverio</i>	
Physics-Intuitive Micro-Modeling Circuits (MMC) Inspired by PEEC Models for Emerging Electromagnetic Problems.....	25
<i>Yuhang Dou, Yang Jiang, Ke-Li Wu</i>	
Quantification of Delay and Skew Uncertainty Due to Fiber Weave Effect in PCB Interconnects.....	28
<i>Alex Manukovsky, Yuriy Shlepnev, Shimon Mordooch</i>	
Analyses of Via-In-Pad Plated Over (VIPPO) and Dogbone in Fanout Routing High-Density Interconnects.....	31
<i>Yanyan Zhang, Junyan Tang, Xiaomin Duan, Srijan Datta, Pavel R. Paladhi, Mahesh Bohra, Sungjun Chun, Daniel M. Dreps</i>	
D-Band Flip-Chip Packaging with Wafer-Level Cu-pillar Bumps.....	34
<i>Zhibo Cao, Matteo Stocchi, Christian Wipf, Jens Lehmann, Lei Li, Selin Tolunay Wipf, Matthias Wietstruck, Corrado Carta, Mehmet Kaynak</i>	
Modeling and Analysis of Simultaneous Switching Noise for Full Wafer Scale Chip Core.....	38
<i>Hyunwoo Kim, Seonguk Choi, Joonsang Park, Haeyeon Kim, Keeyoung Son, Junghyun Lee, Jiwon Yoon, Jonghyun Hong, Boogyo Sim, Keunwoo Kim, Taein Shin, Joungho Kim</i>	
Substrate Integrated Coaxial Line Millimeterwave Components Manufactured in Standard PCB.....	41
<i>Laura Van Messem, Arno Moerman, Olivier Caytan, Hendrik Rogier, Sam Lemey</i>	

Broadband RF Interconnects in a Multi-Layer Advanced Packaging with a Si Interposer	44
<i>Sofia Mvokany, Jack Molles, Zoya Popovic</i>	
Stochastic Modeling of Microcontroller Emission.....	47
<i>Aishwarya Gavai, Jan Hansen, Vivek Dhoot, Dipanjan Gope</i>	
Lossy Transmission Line Model Based on the Generalized Method of Characteristics.....	50
<i>Mark Keran, Anestis Dounavis</i>	
Robust and Efficient Design of On-Chip Compact Delay Units Based on Bridged T-Coil.....	53
<i>Han-Ting Lin, Andreas Weisshaar</i>	
Development of High-Speed and Large-capacity 2U MRDIMM: First-ever MRDIMM with Dual PMICs.....	56
<i>Jonghoon J. Kim, Jinseong Yun, Kyundong Lee, Rakjoo Sung, Jihye Yang, Sanghyuk Yoon, Young-Ho Lee, Kyoungsun Kim, Jeonghyeon Cho, Hoyoung Song</i>	
S-Parameter-Based Delay Calculations in Low-Cost Module.....	59
<i>Robert Wenzel, Nikhita Baladari</i>	
Design and Analysis of Redistribution Layer Interposer Channel Considering Signal Integrity for High Bandwidth Memory Module	62
<i>Jiwon Yoon, Hyunwook Park, Hyunwoo Kim, Boogyo Sim, Jonghyun Hong, Seongguk Kim, Keeyoung Son, Keunwoo Kim, Yigyeong Kim, Sujin Park, Youngsu Kwon, Joungho Kim</i>	
HBM3 PPA Performance Evaluation by TSV Model with Micro-Bump and Hybrid Bonding.....	65
<i>Li-Hsin Huang, Yu-Ying Cheng, Tzong-Lin Wu</i>	
Simple Extraction of the First Resonant Frequency Via Integral Equation Method.....	68
<i>Riccardo Torchio, Francesco Lucchini</i>	
Broadband Launcher-In-Package Using HDI Substrate for Radar Applications	71
<i>Nikita Mahjabeen, Robert Wenzel, Tingdong Zhou</i>	
PCB-Level Jitter Sensitivity Measurement and Hierarchical PDN-Z Based PSIJ Estimation for PCIe Gen5 SSD.....	74
<i>Youngjun Ko, Jinwook Song, Seokwoo Hong, Hyunwoo Kim, Chorom Jang, Sungwoo Jin, Sungwon Roh, Jinan Lee, Jonghee Jeong, Kyungsuk Kim, Jonggyu Park</i>	
Crosstalk Mitigated On-Chip Interconnect Design for High-speed Network-on-Chip (NoC) of Full Wafer Scale Chip (FWSC)	77
<i>Juneyoung Kim, Seonguk Choi, Seongguk Kim, Jihun Kim, Boogyo Sim, Junghyun Lee, Taein Shin, Hyunwoo Kim, Jonghyun Hong, Haeyeon Kim, Joonsang Park, Joungho Kim</i>	
Versatile Genetic Algorithm-Bayesian Optimization(GA-BO) Bi-Level Optimization for Decoupling Capacitor Placement	80
<i>Hyunah Park, Haeyeon Kim, Hyunwoo Kim, Joonsang Park, Seonguk Choi, Jihun Kim, Keeyoung Son, Haeseok Suh, Taesoo Kim, Jungmin Ahn, Joungho Kim</i>	
Automated Generation and Correlation of Physics-Based Via Models with Full-Wave Simulation for an SI/PI Database.....	83
<i>Til Hillebrecht, Johannes Alfert, Torsten Reuschel, Christian Schuster</i>	
Package Technology Enabling for 224 Gbps Electrical Signaling	86
<i>Duye Ye, Cemil S Geyik, Zhiguo Qian, Kemal Aygün</i>	

Real-Time Precision Prediction of 3-D Package Thermal Maps Via Image-to-Image Translation	89
<i>Michael Joseph Smith, Seunghyun Hwang, Vinicius Cabral Do Nascimento, Qiang Qiu, Cheng-Kok Koh, Ganesh Subbarayan, Dan Jiao</i>	
Efficient Boundary Element Methodology for Analyzing Interconnects in Multilayered PCBs.....	92
<i>Giacomo Bianconi, Daniel De Araujo, James Pingenot, Swagato Chakraborty</i>	
A Computational Framework on Pinhole Damage in Ultrathin Barriers for Flexible Electronics Encapsulation	95
<i>Cagan Diyaroglu, Mohammad Taghi, Mohammadi Anaei, Kyungjin Kim</i>	
Efficient Uncertainty Quantification Using Sensitivity Information in Least Squares SVM	98
<i>Karanvir S. Sidhu, Roni Khazaka</i>	
Prior Knowledge Accelerated Transfer Learning (PKI-TL) for Machine Learning Assisted Uncertainty Quantification of MLGMR Interconnect Networks	101
<i>Asha Kumari Jakhar, Surila Guglani, Avirup Dasgupta, Sourajeet Roy</i>	
High Speed Digital Signaling in Printed, Planar Microwave Connectors with Multiple Signal Lines.....	104
<i>Jotham Kasule, Alkim Akyurtlu, Craig Armiento</i>	
Active Mode-Conversion-noise Suppressor with Individual Power-supply Control for Automotive Power-over-data-line Communication.....	107
<i>Yutaka Uematsu</i>	
Signal Integrity Design and Analysis of Redistribution Layer Interposer Channel with Diagonal Meshed Ground in Memory Interface of High Bandwidth Memory	110
<i>Jonghyun Hong, Jiwon Yoon, Hyunwoo Kim, Keeyoung Son, Seonguk Choi, Junghyun Lee, Keunwoo Kim, Joonsang Park, Seongguk Kim, Boogyo Sim, Joungho Kim</i>	
On the Phase Estimation Amplitudes in the Quantum Matrix Equation Solver	113
<i>Xinbo Li, Christopher Phillips, Ian Jeffrey, Vladimir Okhmatovski</i>	
Design and Analysis of an Irregular-Shaped Power Distribution Network (PDN) for High Bandwidth Memory (HBM) Interposer	116
<i>Joonsang Park, Seongguk Kim, Keeyoung Son, Haeyeon Kim, Hyunwoo Kim, Hyunsik Kim, Seonguk Choi, Jihun Kim, Joungho Kim</i>	
Balancing-Based Model Reduction for Fast Power Integrity Verification	119
<i>Antonio Carlucci, Stefano Grivet-Talocia, Scott Mongrain, Sid Kulasekaran, Kaladhar Radhakrishnan</i>	
Improving Accuracy of Rational Macromodels Under Realistic Loading Conditions	122
<i>Antonio Carlucci, Tommaso Bradde, Stefano Grivet-Talocia</i>	
A Flexible Neural Network-Based Tool for Package Second Level Interconnect Modeling.....	125
<i>Furkan Karatoprak, Ekin Su Saçin, Doganay Özese, Ahmet C. Durgun, Mustafa Gökçe Baydoğan, Kemal Aygün, Tolga Memioğlu</i>	
Analysis of Electrostatically Induced Interconnect Structures in Single-Layer Graphene Via a Conservative First-Principles Modeling Technique.....	128
<i>Emile Vanderstraeten, Dries Vande Ginste</i>	
Analysis of Differential Stripline Routing Approaches Within a PCB Via Field for Crosstalk Mitigation	131
<i>Srijan Datta, Yuechen Wang, Junyan Tang, Xianbo Yang, Yanyan Zhang, Pavel R. Paladhi, Mahesh Bohra, Joshua C. Myers, Sungjun Chun, Daniel M. Dreps</i>	

Method of Exploring HVM Process Corner Cases for Loss and Impedance in High Speed Designs	134
<i>Hyunsu Chae, David Z. Pan, Adam Klivans, Bhyrav Mutnury, Douglas Winterberg, Douglas E. Wallace, Arun Chada</i>	
Fast and Accurate Calculation of Mutual Inductance in the Presence of Conductive and Magnetic Media.....	137
<i>Dyuti Sengupta, Andreas Weisshaar</i>	
Contact Resistance of 3D-Printed Interconnects to Thin-Film Metals for Advanced Packaging	140
<i>Jacob Dawes, Alyssa Estenson, Matthew L. Johnston</i>	
Signal and Power Integrity Design of Advanced Interface Bus (AIB) for FPGA Packages.....	143
<i>Brian Wang, Guang Chen, Loke Yip Foo, Xiaohong Jiang</i>	
Generative Multi-Physics Models for System Power and Thermal Analysis Using Conditional Generative Adversarial Networks.....	146
<i>Priyank Kashyap, Chris Cheng, Yongjin Choi, Paul Franzon</i>	
Signal/Power Integrity Co-Simulation of Die-to-Die Interface Customized for Augmented Reality.....	149
<i>Ashkan Hashemi, Koichi Yamaguchi, Bardia Bozorgzadeh, Ling Jiang, Harsha Manjunath, Mahmoud Reza Ahmadi, Wendemegnehu Beyene</i>	
Batch Training of Gaussian Process for Up-Sampling Problems in S-Parameter Predictions.....	152
<i>Yiliang Guo, Xingchen Li, Yifan Wang, Rahul Kumar, Madhavan Swaminathan</i>	
Full Wave IBM Plasma Substrate Benchmark by Cadence Clarity.....	155
<i>Simian Sun, Frank Zavosh, Zhiping Yang, Qin Liu, Suomin Cui, Lijun Jiang</i>	
Integral Equation-Based Solver for the Simulation of Integrated Circuit Packages.....	158
<i>Hans Schreckenbach, Santosh Janaki Raman, Andre Fecteau, Nima Chamanara, David Abraham, Randy Yee, Jonatan Aronsson</i>	
Full-Wave Analysis of Interconnects in Finite Substrates with Layered Media Formulation of SVS-EFIE for 3D Composite Metal-Dielectric Structures	161
<i>Alireza Niazi, Shucheng Zheng, Chris Nguyen, Vladimir Okhmatovski</i>	
A New Perspective on Quasi-TEM Behavior in Microstrip Transmission Lines	164
<i>Aditya Rao, Eric Bogatin, Melinda Piket-May, Mohammed Hadi</i>	
System Aware Floorplanning for Chip-Package Co-design	167
<i>Tse-Han Pan, Paul D. Franzon, Vaishnav Srinivas, Mahalingam Nagarajan, Darko Popovic</i>	
Interconnect Modelling Sensitivity Studies for High Signaling Data Rates.....	170
<i>Adewale K. Oladeinde, Jose A. Hejase</i>	
Efficient Estimation of Power Supply Induced Jitter Via Machine Learning.....	173
<i>Ahsan Javaid, Ramachandra Achar, Jai Narayan Tripathi</i>	
Machine-Learning-Based Constrained Optimization of a Test Coupon Launch Using Inverse Modeling	176
<i>Andrew Page, Xu Chen</i>	
Wideband Complex Vector Fitting for Modeling Time Delay Variations in Passive Photonic Filters	179
<i>Thijs Ullrick, Dirk Deschrijver, Wim Bogaerts, Tom Dhaene</i>	

Author Index